

**N-CHANNEL ENHANCEMENT MODE MOSFET**

General Description

RMP7N80 is an N-channel enhancement mode MOSFET, which uses the self-aligned planar process and improved terminal technology, reducing the conduction loss, enhancing the avalanche energy.

MAIN CHARACTERISTICS

$V_{DSS}$	800	V
$I_D$	7.0	A
$R_{DS(ON)}$	2.0	$\Omega$
$C_{rSS}$	12	pF

FEATURES

- Low Crss
- Low gate charge
- Fast switching
- Improved ESD capability
- Improved dv/dt capability
- 100% avalanche energy test

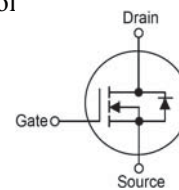
APPLICATIONS

- High efficiency switch mode power supplies
- Electronic lamp ballasts
- UPS

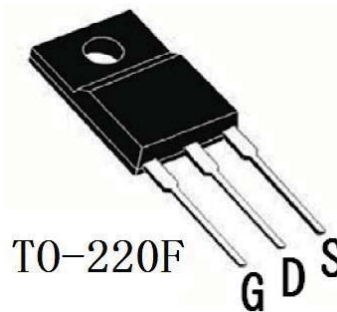
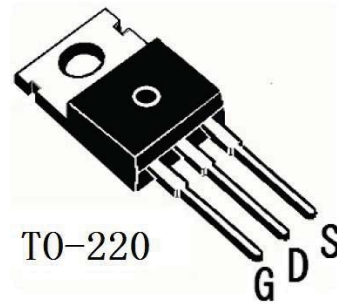
Package Marking And Ordering Information

Device	Device Package	Marking
RMP7N80TI	TO-220F	7N80
RMP7N80T2	TO-220	7N80

Symbol



Package



## ABSOLUTE MAXIMUM RATINGS (Tc = 25°C)

Parameter	Symbol		Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>		800	V
Continues Drain Current	I <sub>D</sub>	Tc=25°C	7*	A
		Tc=100°C	4.0*	
Plused Drain Current (note 1)	I <sub>DM</sub>		28	A
Gate-to-Source Voltage	V <sub>GS</sub>		±30	V
Single Pulsed Avalanche Energy (note2)	E <sub>AS</sub>		418	mJ
Avalanche Current (note1)	I <sub>AR</sub>		7.0	A
Repetitive Avalanche Energy (note 1)	E <sub>AR</sub>		18	mJ
Peak Diode Recovery (note3)	dv/dt		4.5	V/ns
Power Dissipation	P <sub>D</sub> Tc=25°C	TO-220	140	W
		TO-220F	49	
Power Dissipation Derating Factor	P <sub>D(DF)</sub> Above 25°C	TO-220	1.12	W/°C
		TO-220F	0.39	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>		150, -55~+150	°C
Maximum Temperature for Soldering	T <sub>L</sub>		300	°C

## THERMAL CHARACTERIATIC

Parameter	Symbol		Max	Unit
Thermal Resistance, Junction to Case	R <sub>th(j-c)</sub>	TO-220	0.89	°C/W
		TO-220F	2.55	
Thermal Resistance, Junction to Ambient	R <sub>th(j-A)</sub>	TO-220	62.5	°C/W
		TO-220F	62.5	

\* Drain current limited by maximum junction temperature

Off-Characteristics						
Parameter	Symbol	Tests Conditions	Min	Type	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0V$	800	-	-	V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$I_D=250\mu A$ , referenced to 25°C	-	0.7	-	V/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=800V, V_{GS}=0V, T_C=25^\circ C$	-	-	10	$\mu A$
		$V_{DS}=640V, T_C=125^\circ C$	-	-	100	
Gate-body leakage current, forward	$I_{GSSF}$	$V_{DS}=0V, V_{GS}=30V$	-	-	100	nA
Gate-body leakage current, reverse	$I_{GSSR}$	$V_{DS}=0V, V_{GS}=-30V$	-	-	-100	nA

On-Characteristics						
Parameter	Symbol	Tests Conditions	Min	Type	Max	Unit
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	-	4.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=3.5A$	-	1.6	2.0	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS}=40V, I_D=3.5A$ (note4)	-	5.0	-	S

Dynamic Characteristics						
Parameter	Symbol	Tests Conditions	Min	Type	Max	Unit
Input capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$	-	1300	1690	pF
Output capacitance	$C_{oss}$		-	125	160	pF
Reverse transfer capacitance	$C_{rss}$		-	12	15	pF

Switching Characteristics						
Parameter	Symbol	Tests Conditions	Min	Type	Max	Unit
Turn-On delay time	$t_{d(on)}$	$V_{DD}=400V, I_D=7A, R_G=25\Omega$ (note 4, 5)	-	35	80	ns
Turn-On rise time	$t_r$		-	100	210	ns
Turn-Off delay time	$t_{d(off)}$		-	50	110	ns
Turn-Off Fall time	$t_f$		-	60	130	ns
Total Gate Charge	$Q_g$	$V_{DS}=640V, I_D=7A, V_{GS}=10V$ (note 4, 5)	-	27	35	nC
Gate-Source charge	$Q_{gs}$		-	8.2	-	nC
Gate-Drain charge	$Q_{gd}$		-	11	-	nC

Drain-Source Diode Characteristics and Maximum Ratings						
Parameter	Symbol	Tests Conditions	Min	Type	Max	Unit
Maximum Continuous Drain-Source Diode Forward Current		$I_S$	-	-	7	A
Maximum Pulsed Drain-Source Diode Forward Current		$I_{SM}$	-	-	28	A
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=7A$	-	-	1.4	V
Reverse recovery time	$t_{rr}$	$V_{GS}=0V, I_S=7A$ $di_F/dt=100A/\mu s$ (note 4)	-	650	-	ns
Reverse recovery charge	$Q_{rr}$		-	7.0	-	$\mu C$

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2:  $L=16mH, I_{AS}=7A, V_{DD}=50V, R_G=25\Omega$ , Starting  $T_J = 25^\circ C$
- 3:  $I_{SD} \leq 7A, di/dt \leq 300A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ C$
- 4: Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
- 5: Essentially independent of operating temperature

# RATING AND CHARACTERISTICS CURVES (RMP7N80TI/T2)

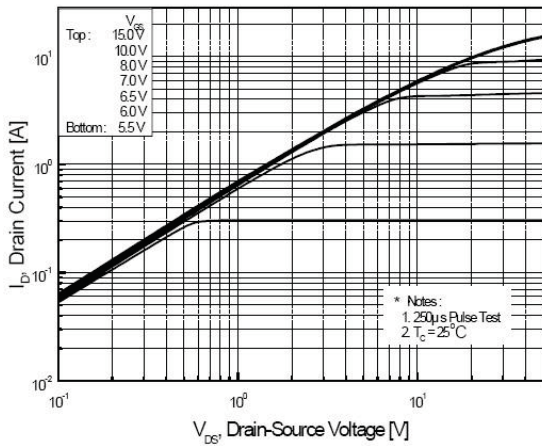


Fig. 1 On-State Characteristics

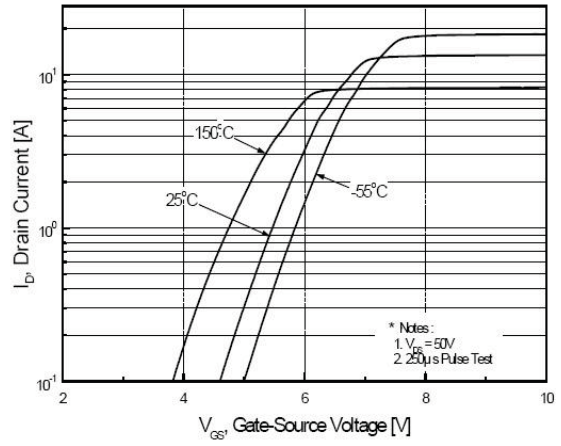


Fig. 2 Transfer Characteristics

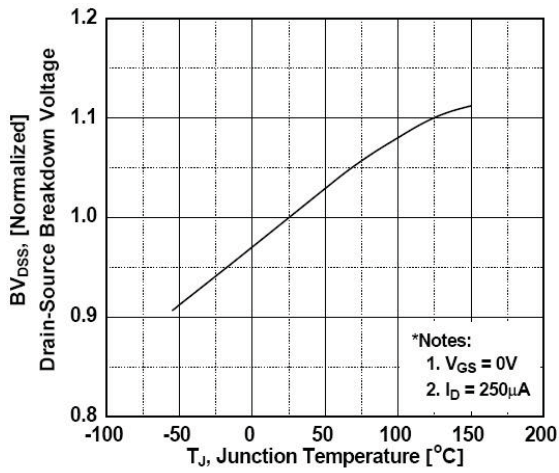


Fig. 3 Breakdown Voltage Variation vs Temperature

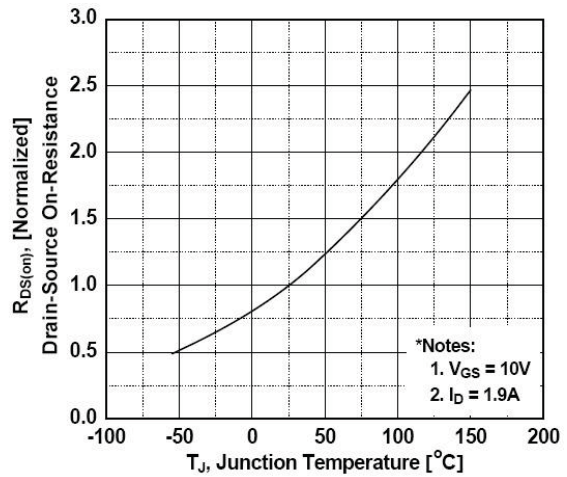


Fig. 4 On-Resistance Variation vs Temperature

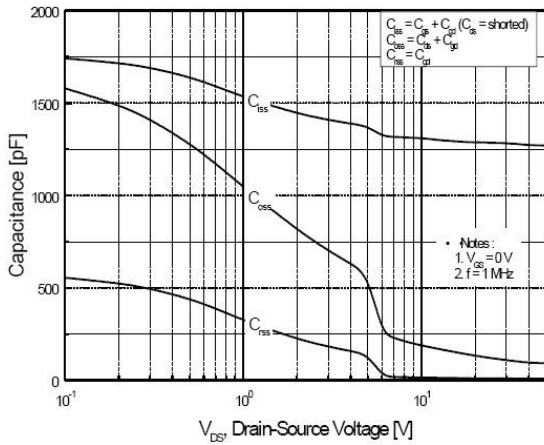


Fig. 5 Capacitance Characteristics

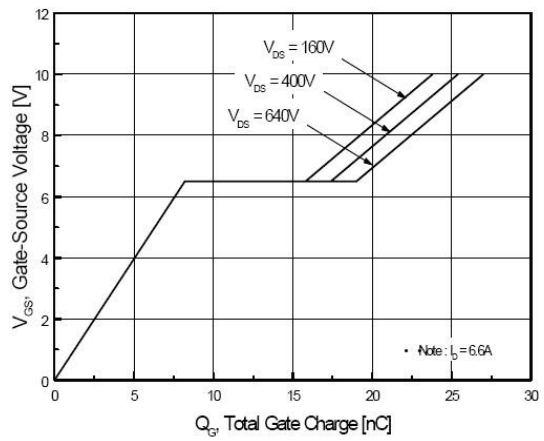


Fig. 6 Gate Charge Characteristics

## RATING AND CHARACTERISTICS CURVES (RMP7N80TI/T2)

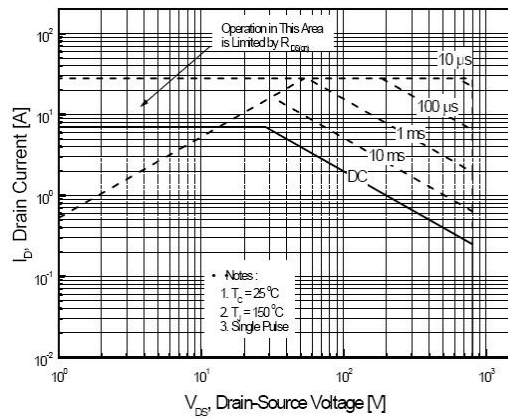


Fig. 7 Maximum Safe Operating Area

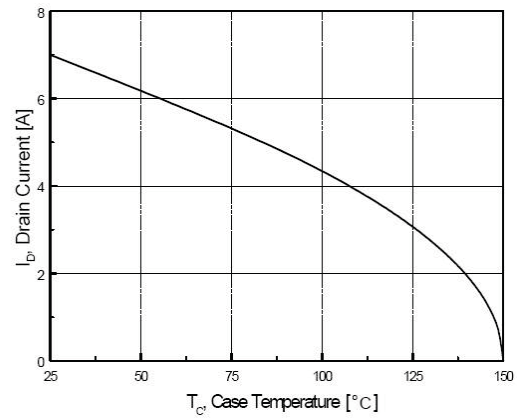


Fig. 8 Maximum Drain Current vs Case Temperature

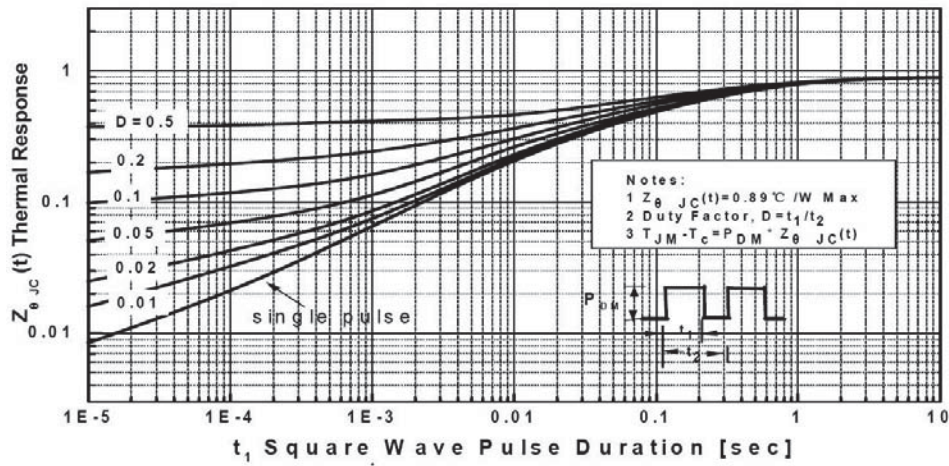


Fig. 9 Transient Thermal Response Curve(TO-220)

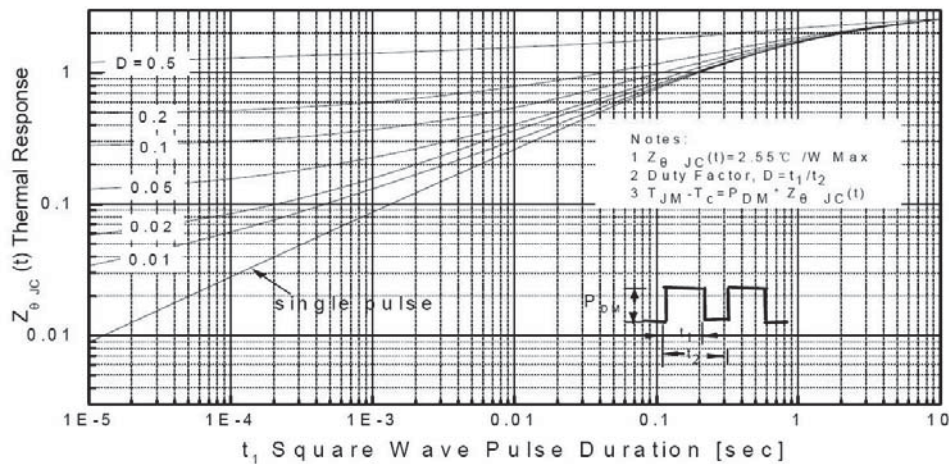


Fig. 10 Transient Thermal Response Curve(TO-220F)



## TEST CIRCUITS AND WAVEFORMS

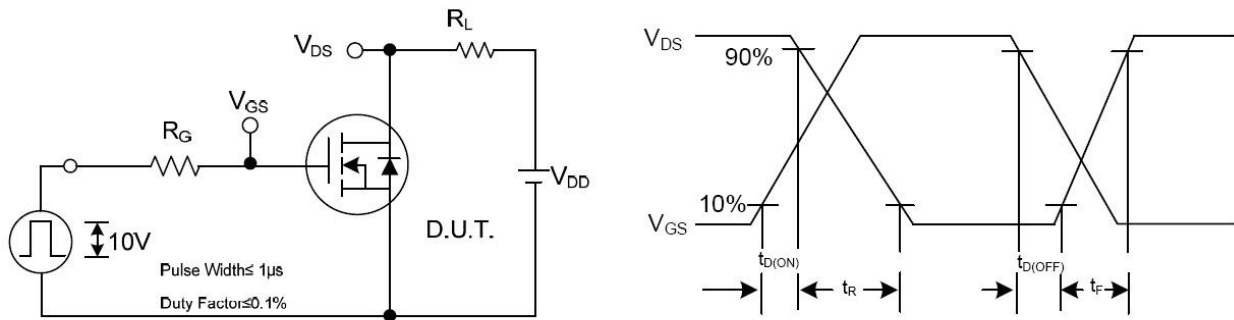


Fig.11 Resistive Switching Test Circuit & Waveforms

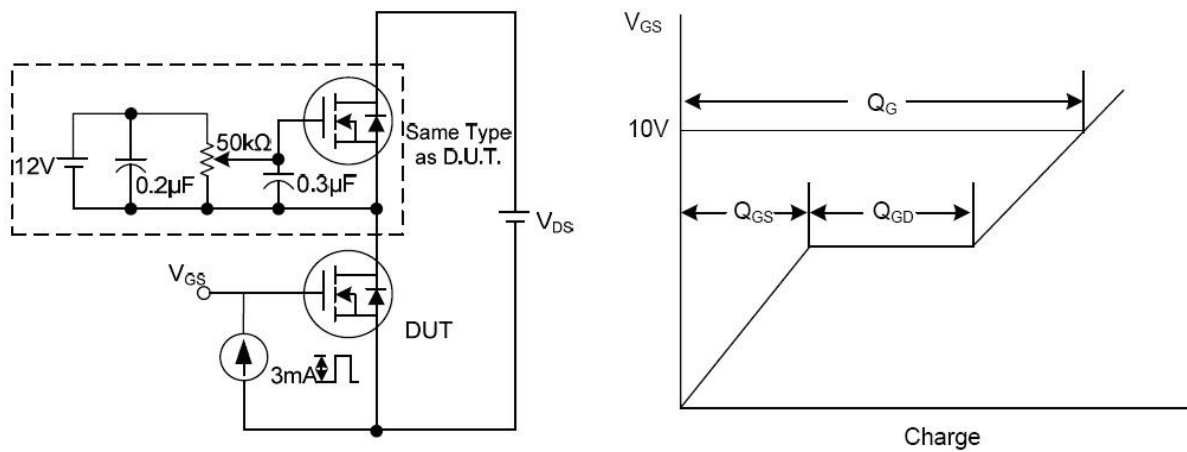


Fig.12 Gate Charge Test Circuit & Waveform

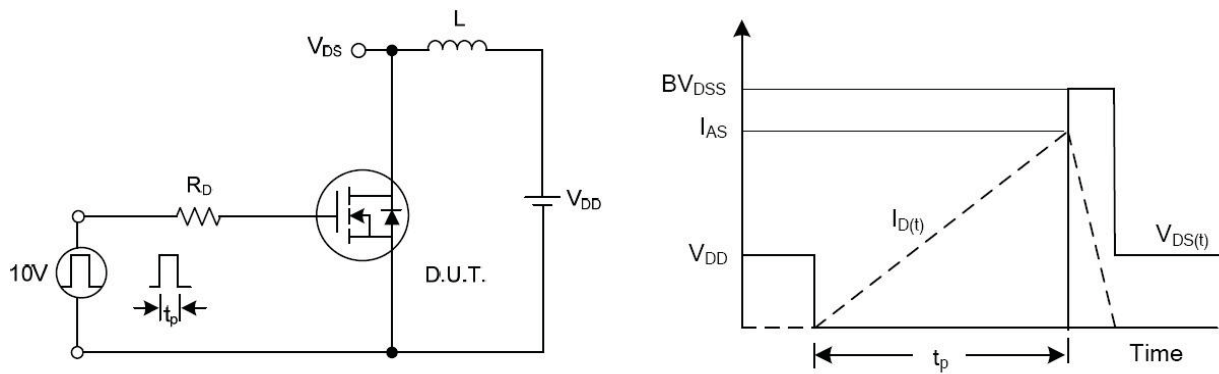
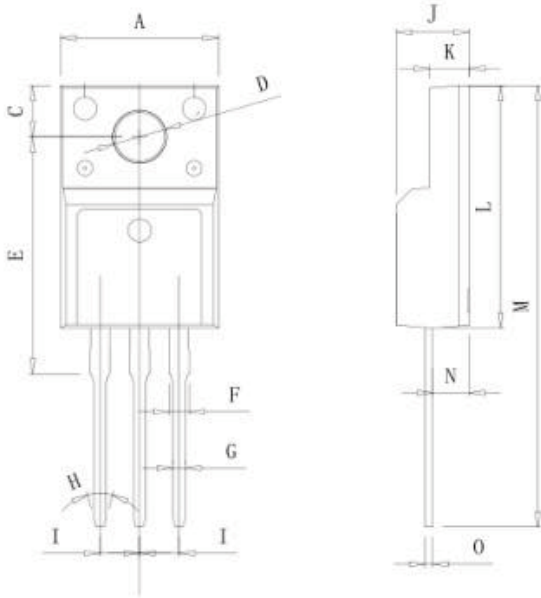


Fig.13 Unclamped Inductive Switching Test Circuit & Waveforms

# TPACKAGE MECHANICAL DATA

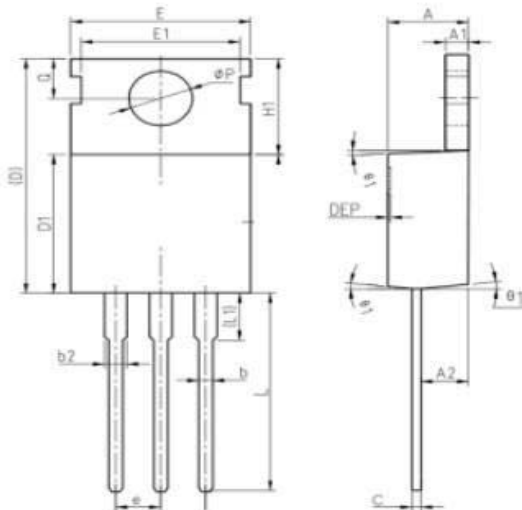
## T0-220F 外形尺寸



单位: MM

SYMBOL	MILLIMETERS		SYMBOL	MILLIMETERS	
	Min	Max		Min	Max
A	9.96	10.36	K	2.34	2.74
J	4.5	4.9	O	0.4	0.6
M	28	29.6	G	0.7	0.9
E	15.4	15.6	D	2.9	3.3
L	15.5	16.1	C	3.25	3.5
N	2.2	2.9	I	2.54 TYP	
F		1.4			

## T0-220A 外形尺寸



单位: MM

SYMBOL	MILLIMETERS		SYMBOL	MILLIMETERS	
	Min	Max		Min	Max
A	4.2	4.8	C	0.4	0.6
D1	8.9	9.4	b	0.7	0.9
E	9.7	10.3	A1	1.2	1.4
H1	6.3	6.9	Q	2.7	2.9
b2	1.27	1.43	A2	2.3	2.5
$\varnothing P$	3.6	3.9	e	2.54 TYP	
D	15.5	15.7			